

SPECIFICATION AND PERFORMANCE

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Scope:

This specification covers the requirements for product performance, test methods and quality assurance provisions of below

Part Name	Description
104I-TA01	SD 4.0 Socket, Top Mount, Push-Push Type, w/switch/card lock, G/F, Reel

Performance and Descriptions:

The product is designed to meet the electrical, mechanical and environmental performance requirements specification. Unless otherwise specified, all tests are performed at ambient environmental conditions.

RoHS:

All material in according with the RoHS environment related substances list controlled.

MATERIALS			
NO.	PART NAME	DESCRIPTION	
1	HOUSING	LCP UL94V-0 Black	
2	CONTACT	Phosphor Bronze, gold flash on contact area, tin plating on solder tails, under plating nickel	
3	SHELL	Stainless steel 0.2t, G/F on solder tails, under plating nickel over all	
4	SLIDER	LCP UL94V-0 Black	
5	LINK	Stainless steel	
6	SPRING	SWP-B	

RATING		
Rated Current	1A Max	
Rated Voltage	30V AC/DC	
Operating Temperature	-40°~+85°	
Storage Temperature	-40°~+85°	
Durability	5000 cycles by UHS-II Card (office environment)	

ELECTRICAL			
Item	Requirement	Test Condition	
Contact Resistance	100 mΩ Max.	Mate card measured dry circuit, 20m volts Max. 1mA Max. EIA-361-23	
Insulation Resistance	1000 MΩ Min Initial 100 MΩ Min Final	Apply 500V DC between adjacent pins or pin and ground. EIN-364-21	
Dielectric Withstanding	No breakdown	Apply 500V AC for 1 minute between adjacent	

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Voltage		terminals and ground. EIA-364-20
Temperature Rising	Based upon 30deg. C rise above ambient temperature.	EIA-364-70 Mate connectors, measure the temperature rise at rated current after 0.5A/Power contact. The temperature rise above ambient shall not exceed 30°C the ambient condition is still air at 25°C.

MECHANICAL			
Item	Requirement	Test Condition	
Total Insertion Force	40 N Max.	Push the card in at the speed rate of 25±3mm/minute. EIA-364-13	
Withdrawal Force	0.5 N Min.	Drag the card out at the speed rate of 25±3mm/minute. EIA-364-13	
Durability	Appearance no damage. After test contact resistance $100m\Omega$ Max.	Insertion and extraction are repeated 10,000 cycles with the card at the speed rate of 400-600 cycles/hour. EIA-364-09	
Vibration	No mechanical damage shall occur on the prats Shall not cause current interruption greater than 100 ns	Mate card and subject to the following vibration conditions, for a period of 2 hours in each of 3 mutually perpendicular axes, passing DC 1Ma during the test. Amplitude: 1.50mm p-p or 19.6m/s^2 (2G) Frequency: 10-55-10Hz Shall be traversed in 1minute. EIA-364-28	

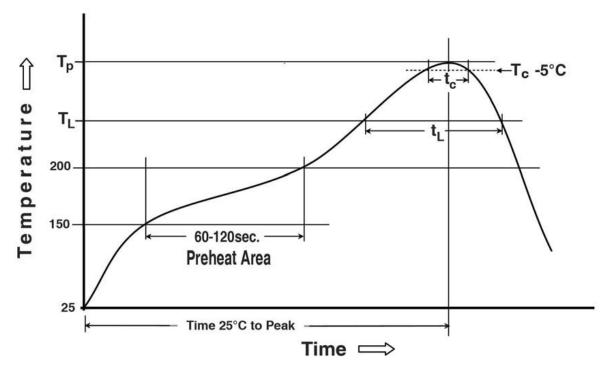
ENVIRONMENTAL			
Item	Requirement	Test Condition	
Humidity	Appearance no damage. After test contact resistance $100m\Omega$ Max.	Temperature: 40°C+2°C Humidity: 90%(RH) Period: 8 hours EIA-364-31, Test condition A method III	
Thermal Shock	Appearance no damage. After test contact resistance 100mΩ Max.	Absolute humidity: $\leq 20g/m^3$ Subject mated connectors to 24 cycles between -40° to +85°C. One cycle: 85°C/ 45 minutes, 15 seconds change to -40°C, -40°C/ 45 minutes, 15 seconds change to 85°C. EIA-364-32, Test condition I	
Salt Spray	Appearance no damage. After test contact resistance 100mΩ Max.	Mate card and exposed to the following salt mist conditions. Upon completion of the exposure period, salt deposits shall be removed by a gentle wash or dip in running water, after which the specified measurements shall be performed. 5% NaCl solution, spray time 24 hours Ambient temperature: 35°C EIA-364-26	

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SOLDER ABILITY		
Item	Requirement	Test Condition
Solder Ability	95%MIN of immersed area Must show no voids.	Temperature: 260°C+5°C Time: 10s MAX EIA-364-52
Resistance to soldering heat	Appearance no damage	Solder time: 10s MAX. Solder temperature: 260°C±5°C

Reflow Profile



Preheating temperature: 150 ~ 200°C, 60~120 seconds Liquidus temperature (TL): 217°C, 60~150 seconds Peak temperature: 260°C Time within 5 °C of peak temperature (Tc): 255°C, 30seconds

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